

METHOD OF GRINDING BACK SURFACE OF SEMICONDUCTOR WAFER
AND SEMICONDUCTOR WAFER GRINDING APPARATUS

5

ABSTRACT OF THE DISCLOSURE

10 A semiconductor wafer back-surface grinding method,
for grinding a back surface of a semiconductor wafer, an
opposed front surface of the semiconductor wafer being
adhered to a support base material and being provided
with a circuit pattern, including: measuring an initial
15 thickness of the semiconductor wafer before grinding, in
a condition where the support base material is adhered to
the front surface of the semiconductor wafer; obtaining a
cutting depth by subtracting a set final thickness
measured after grinding from the initial thickness; and
20 grinding the back surface of the semiconductor wafer,
based on the cutting depth.

Fig. 2